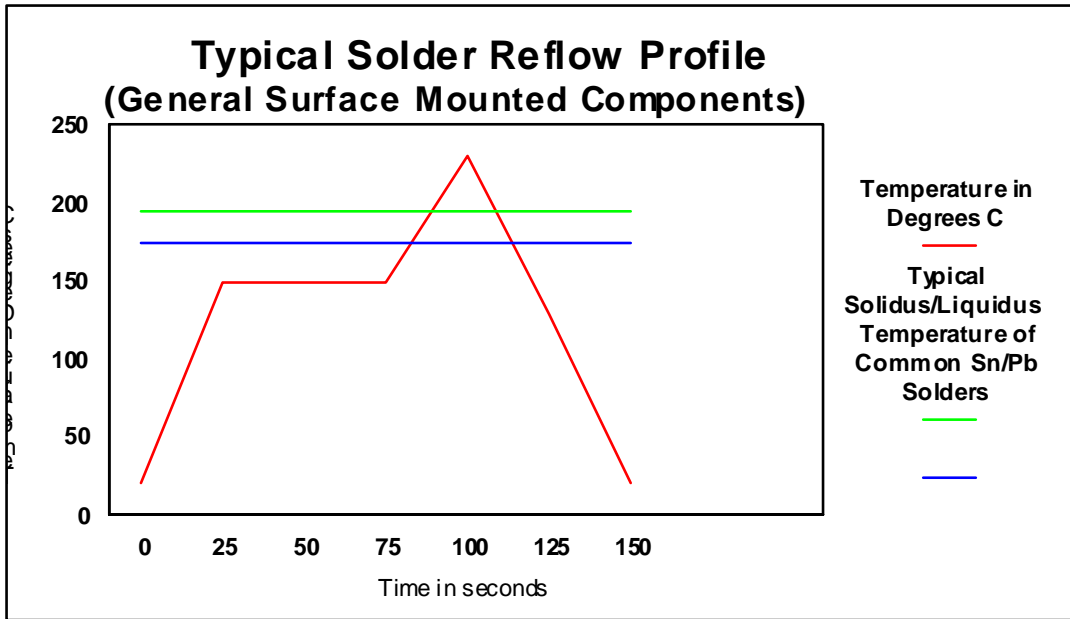


## Typical Soldering Profile For IMS Solderable Components



### Temperature/Duration Limit Recommendations

PEAK TEMPERATURE	TIME
260 deg C (500 deg F)	5 Seconds
250 deg C (482 deg F)	10 Seconds
240 deg C (464 deg F)	20 Seconds
230 deg C (446 deg F)	30 Seconds
204 deg C (400 deg F)	40 Seconds

Although specific applications will vary and many other variables will need to be considered such as board type, adjacent components, and delivery methods for the solder, using a standard Mil grade solder (ie. SN-62) and a good Mil grade RA or RMA flux, the profile depicted above will typically give good results.

Note: Regarding Aluminum Nitride Components: ALN is very thermally conductive. Contact style soldering methods that do not consider the heat-sync properties of these high thermally conductive components (ie. Soldering irons and hot air column heating methods) can be difficult to use. Best results occur with hot plate reflow, or belt or chamber reflow methods. ALN has a TC of 170 W/ m/ °K and this high heat conductivity can cool soldering iron tips the instant they come into contact with the component which often results in turning up the heat on the iron much too high to compensate.

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